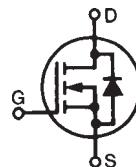


PolarHT™ Power MOSFET

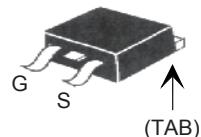
IXTA 110N055P
IXTP 110N055P
IXTQ 110N055P

V_{DSS} = 55 V
 I_{D25} = 110 A
 $R_{DS(on)}$ ≤ 13.5 mΩ

N-Channel Enhancement Mode
Avalanche Rated

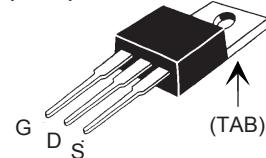


TO-263 (IXTA)

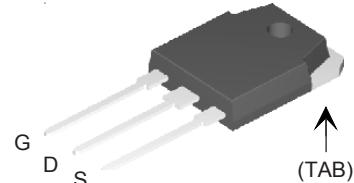


Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ C$ to $175^\circ C$	55		V
V_{DGR}	$T_J = 25^\circ C$ to $175^\circ C$; $R_{GS} = 1 M\Omega$	55		V
V_{GS}	Continuous	±20		V
V_{GSM}	Transient	±30		V
I_{D25}	$T_c = 25^\circ C$	110		A
I_{DRMS}	External lead current limit	75		A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	250		A
I_{AR}	$T_c = 25^\circ C$	110		A
E_{AR}	$T_c = 25^\circ C$	30		mJ
E_{AS}	$T_c = 25^\circ C$	1.0		J
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 A/s$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$, $R_G = 10 \Omega$	10		V/ns
P_D	$T_c = 25^\circ C$	390		W
T_J		-55 ... +175		C
T_{JM}		175		C
T_{stg}		-55 ... +150		C
T_L	1.6 mm (0.062 in.) from case for 10 s	300		C
T_{SOLD}	Plastic body for 10 s	260		C
M_d	Mounting torque (TO-3P / TO-220)	1.13/10		Nm/lb.in.
Weight	TO-3P TO-220 TO-263	5.5 4 3		g

TO-220 (IXTP)



TO-3P (IXTQ)



G = Gate
S = Source
TAB = Drain

Symbol	Test Conditions ($T_J = 25^\circ C$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0 V$, $I_D = 250 A$	55		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 A$	3.0		5.5 V
I_{GSS}	$V_{GS} = \pm 20 V_{DC}$, $V_{DS} = 0$		±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$		25 250	A
$R_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2 \%$	11	13.5	mΩ

Features

- International standard packages
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

Advantages

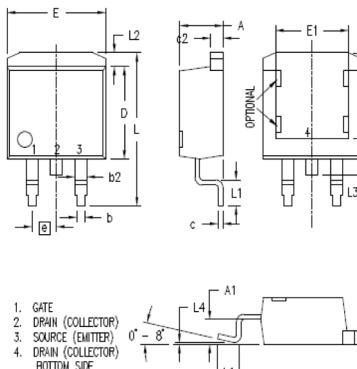
- Easy to mount
- Space savings
- High power density

Symbol **Test Conditions**
Characteristic Values
 $(T_J = 25 \text{ }^{\circ}\text{C}, \text{unless otherwise specified})$
Min. **Typ.** **Max.**

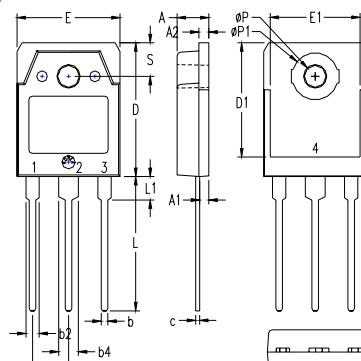
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 I_{D25}$, pulse test	23	36	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	2210	pF	
		1400	pF	
		550	pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 10 \Omega$ (External)	27	ns	
		53	ns	
		66	ns	
		45	ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$	76	nC	
		17	nC	
		33	nC	
R_{thJC}			0.38	C/W
R_{thcs}	(TO-3P)	0.21		C/W
	(TO-220)	0.25		C/W

Source-Drain Diode
Characteristic Values
 $(T_J = 25 \text{ }^{\circ}\text{C}, \text{unless otherwise specified})$

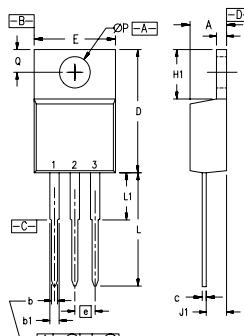
Symbol	Test Conditions	Min.	Typ.	Max.
I_s	$V_{GS} = 0 \text{ V}$			110 A
I_{SM}	Repetitive			250 A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$ Pulse test, $t \leq 300 \text{ s}$, duty cycle $d \leq 2\%$			1.5 V
t_{rr} Q_{RM}	$I_F = 25 \text{ A}, -di/dt = 100 \text{ A/s}$ $V_R = 25 \text{ V}, V_{GS} = 0 \text{ V}$	80	ns	C

TO-263 (IXTA) Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100	BSC	2.54	BSC
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-3P (IXTQ) Outline

1 - GATE
2 - DRAIN (COLLECTOR)
3 - SOURCE (EMITTER)
4 - DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.799	19.80	20.30
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	.215	BSC	5.45	BSC
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
ØP	.126	.134	3.20	3.40
ØP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

TO-220 (IXTP) Outline


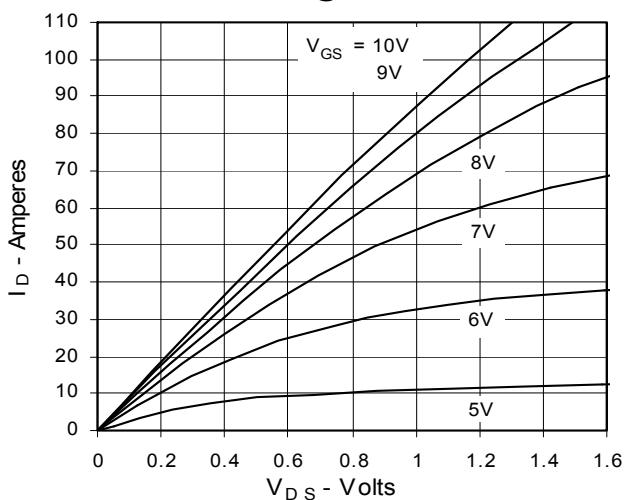
Pins: 1 - Gate 2 - Drain

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100	BSC	2.54	BSC
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

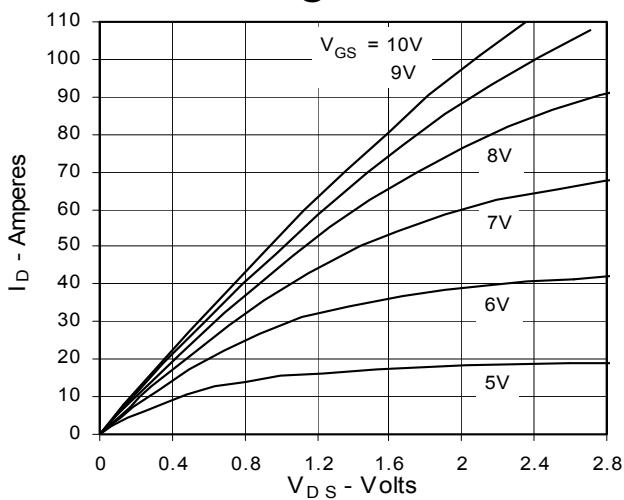
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405B2 6,759,692 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

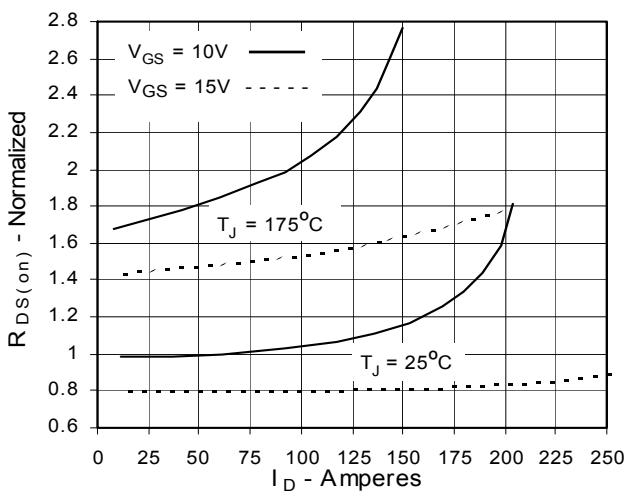
**Fig. 1. Output Characteristics
@ 25°C**



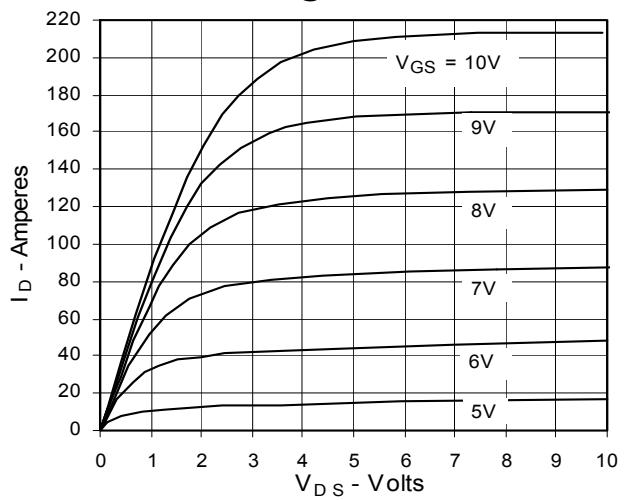
**Fig. 3. Output Characteristics
@ 150°C**



**Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Drain Current**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Junction Temperature**

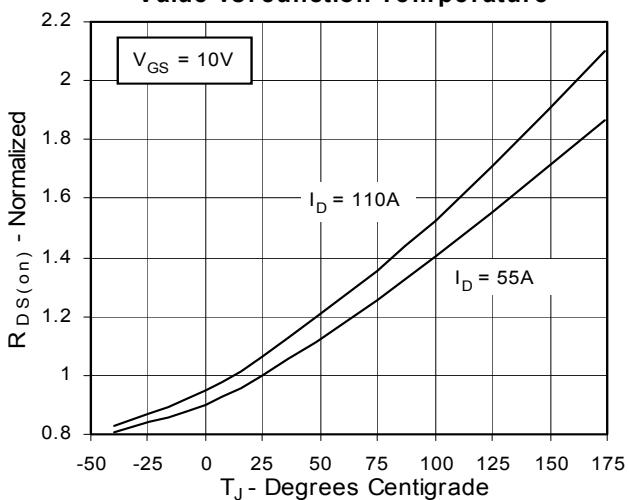


Fig. 6. Drain Current vs. Case Temperature

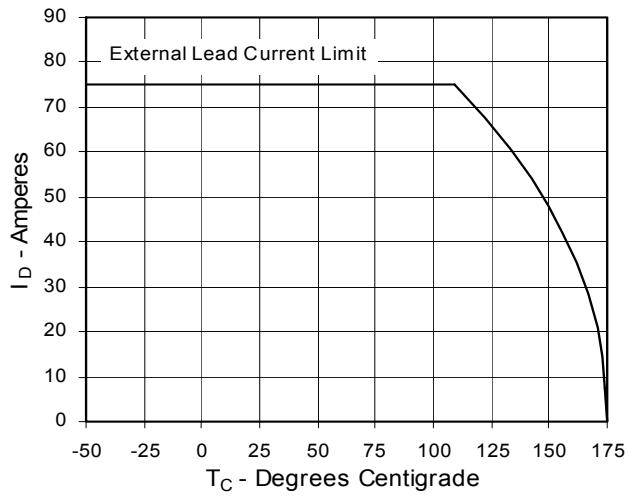


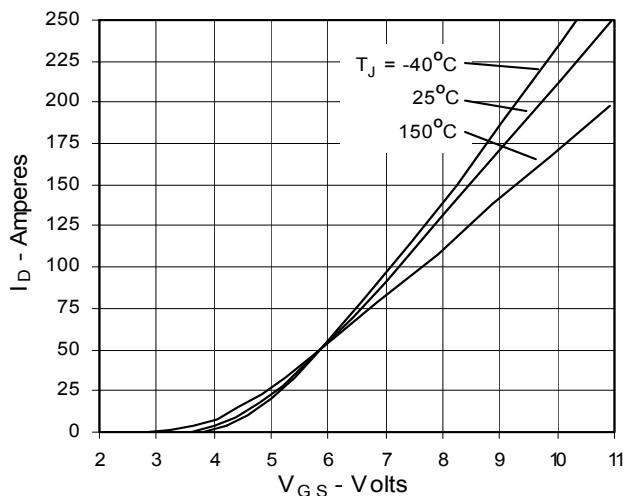
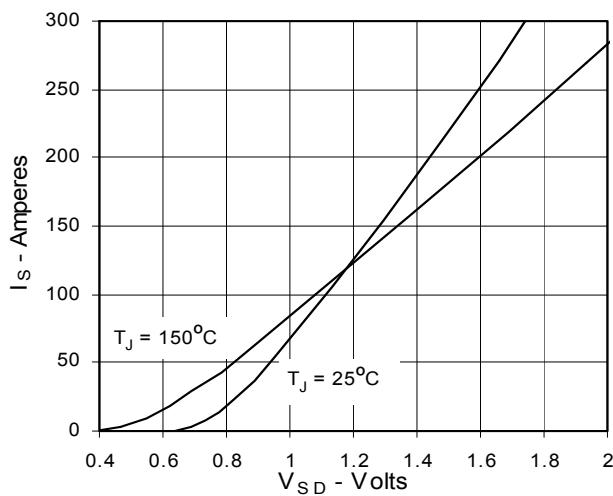
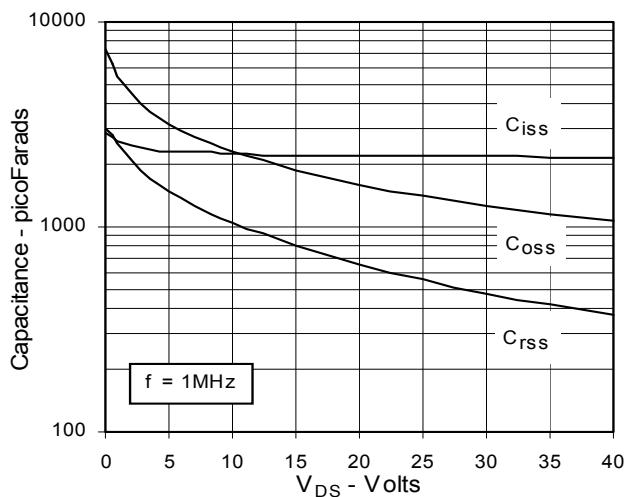
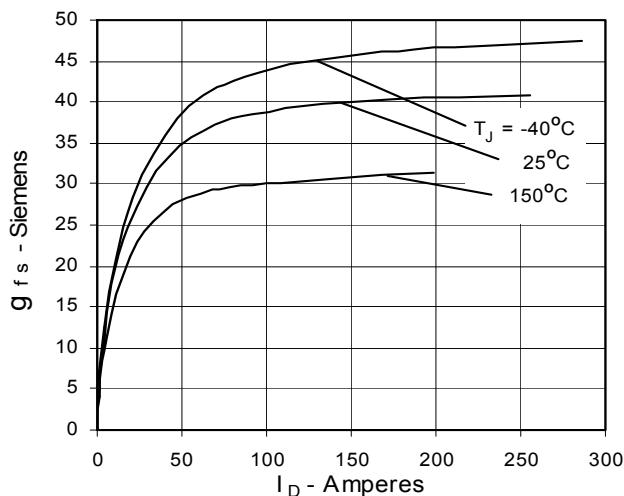
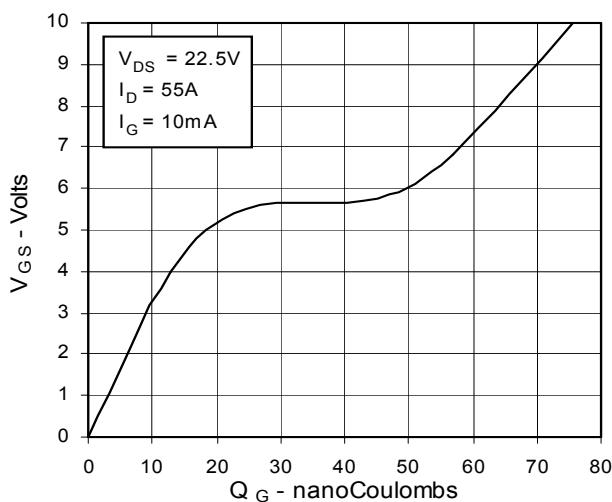
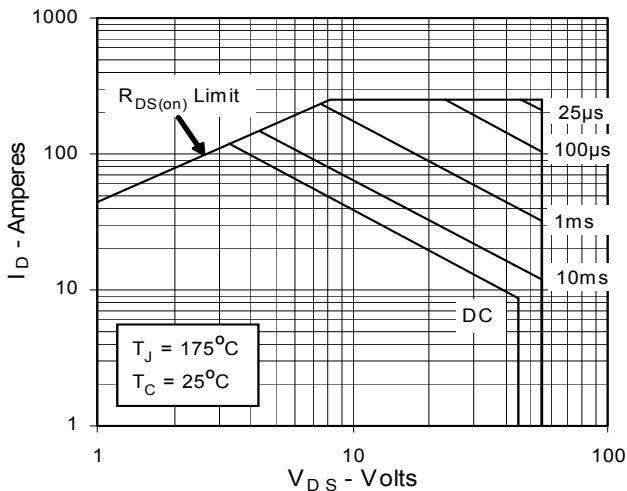
Fig. 7. Input Admittance

**Fig. 9. Source Current vs.
Source-To-Drain Voltage**

Fig. 11. Capacitance

Fig. 8. Transconductance

Fig. 10. Gate Charge

**Fig. 12. Forward-Bias
Safe Operating Area**


Fig. 13. Maximum Transient Thermal Resistance